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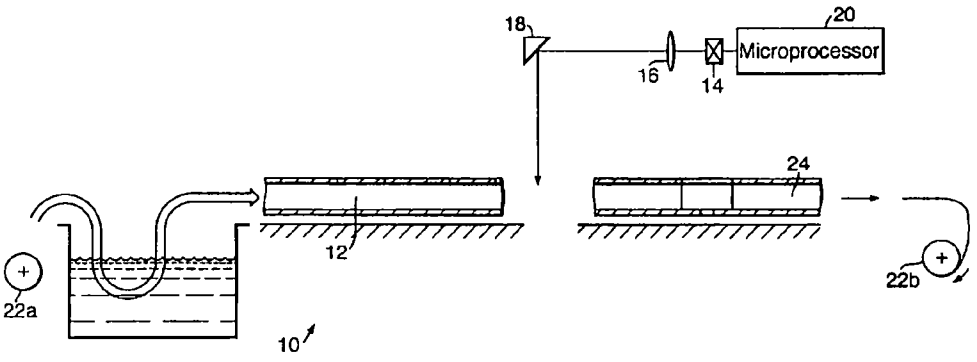
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(54) Title: A METHOD OF FORMING AN OPENING OR CAVITY IN A SUBSTRATE FOR RECEIVING AN ELECTRONIC COMPONENT



(57) Abstract: A method of forming an opening or cavity in a substrate (12), for receiving an electronic component, consists of or includes providing a patterned opaque masking layer (21a) on or adjacent a first major surface of the substrate (12), the masking layer (21a) having an opening overlying the position where the cavity is to be made, removing material from the substrate (12) by laser ablation through the opening thereby forming an opening or cavity of a suitable size for receiving said electronic component.

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